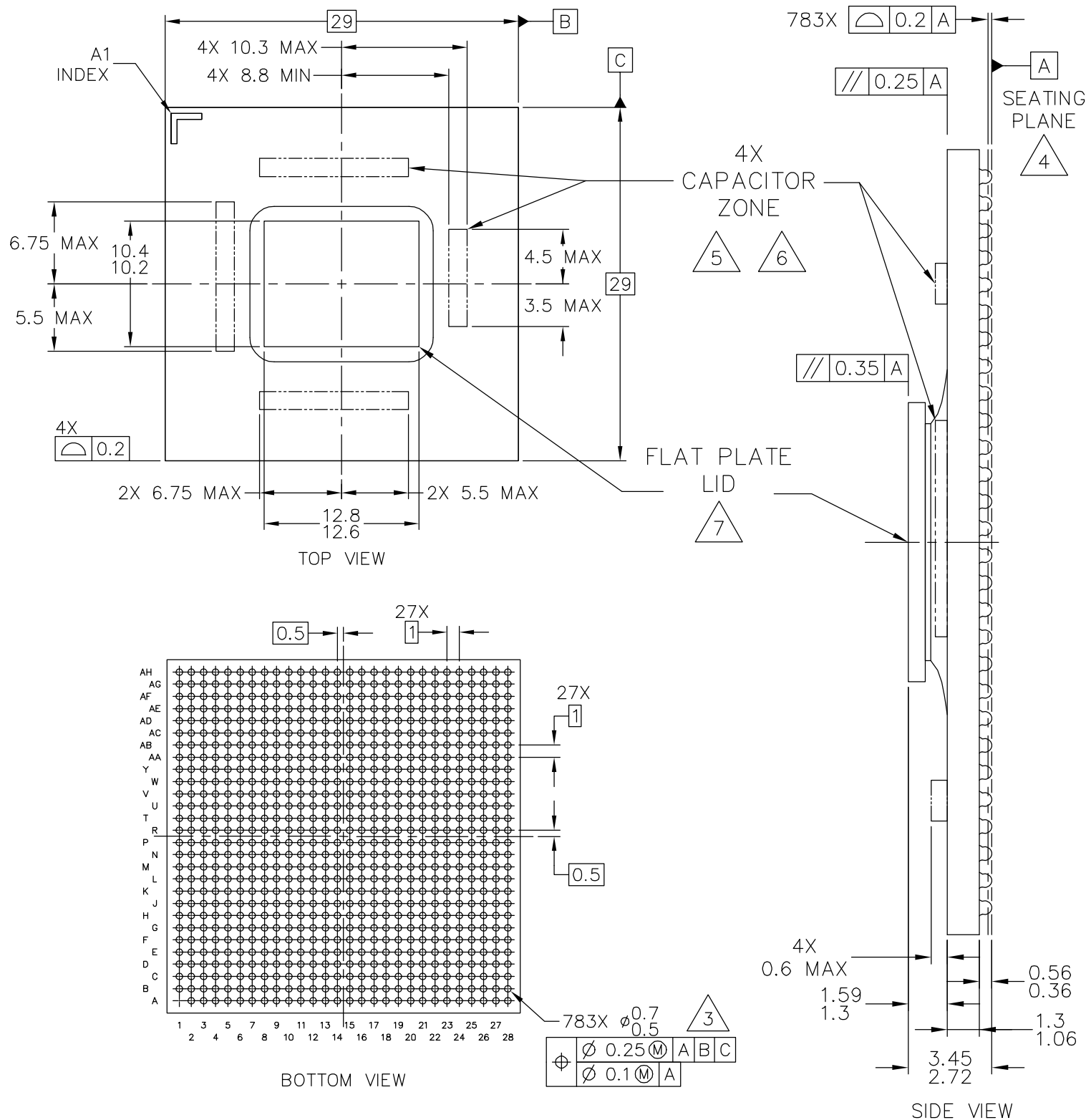






NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
- 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.
- 6. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.
- 7. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
- 8. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.

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TITLE: 783 I/O FC PBGA, 29 X 29 PKG, 1 MM PITCH, WITH CAP ZONES AND LID			DOCUMENT NO: 98ARE10722D		REV: 0
			CASE NUMBER: 1991–01		29 JAN 2008
			STANDARD: JEDEC MS–034		